

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Todd O. Bolken

**Serial No.:** 10/791,192

**Filed:** March 2, 2004

**For:** TWO-STAGE TRANSFER MOLDING  
DEVICE TO ENCAPSULATE MMC  
MODULE

**Confirmation No.:** 1966

**Examiner:** D. Zarneke

**Group Art Unit:** 2891

**Attorney Docket No.:** 2269-4794.4US  
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**Notice of Allowance Mailed:**

May 1, 2007

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July 25, 2007

**FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES  
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Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

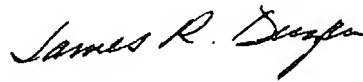
Sir:

1. This letter is to specify that the FEE ADDRESSEE for this patent is:

MICRON TECHNOLOGY, INC.  
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Boise, Idaho 83707-0006

2. The Customer Number for the Fee Addressee is **26809**.
3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,



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